Product Change Notification

107702 - 03

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Product Change Notification

Change Notification #: 107702 - 03

Change Title: Intel® Optical Transceiver TXN174312013xxx XENPAK LR, PCN 107702-03, Manufacturing Site, and Order Code Change, Reason for Revision: Added changes to PCB to improve ESD and EMI performance

Date of Publication: November 21, 2007

Key Characteristics of the Change:

Manufacturing Site
Order Code
New end cap and packaging box
Changes to PCB to improve ESD and EMI Performance

Forecasted Key Milestones:

Date of Qualification Data Availability:	Dec 15, 2007
Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 24, 2007
Date of First Availability of Post-Conversion Material:	Dec 24, 2007

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Reason for Revision: Added changes to PCB to improve ESD and EMI performance

Contract Manufacturer Transfer
The TXN174312013 has a new transponder CM assembly site in Bangkok, Thailand and the specific customer SDKs and Material Master Number (MM#) will change to reflect the new site. The previous assembly site for the TXN174312013 was in Penang, Malaysia.

Changes to PCB to Improve ESD and EMI Performance
1. Re-spin PCB to add pad for capacitor to improve ROSA ESD dissipation.
2. Add second piece of absorber material to improve EMI specification margins.
3. Change TOSA SC clip to a more flexible material (ULTEM 2200), that has been metal plated for improved ESD performance. ROSA SC clip continues to use the PPS material.

4. Include Pb-free LF ROHS compliant components that are functionally equivalent to the replaced parts

New End Cap
To enhance the end cap design used on the TXN174312013, Intel will replace the two single end caps for each Tx and Rx port with one end cap for both ports.

New Packaging Box
Intel will use a new packaging box to accommodate the new end cap design and reduce overall packaging box size.

Customer Impact of Change and Recommended Action:

Intel will perform full quality and reliability testing, including 2000 hours testing, and complete design verification testing for TXN179012013 to ensure that there is no quality, reliability or functional implications to our customers. Please contact your local Intel sales representative to request the qualification reports.

Intel will change the product SKU and Material master ID (mm#) with this PCN change. Please refer to the chart below for changes.

Products Affected / Intel Ordering Codes:

Affected Product Code	Pre-Change MM#	Post-Affected Product Code	Post-Change MM#
TXN174312013F06	862100	TXN174312013FY1	891479
TXN174312013F11	864062	TXN174312013FY2	891480
TXN174312013F21	886312	TXN174312013FY3	891481
TXN174312013F12	866072	TXN174312013FY4	891482
TXN174312013F13	866073	TXN174312013FY5	891485
TXN174312013F14	866074	TXN174312013FY6	891486
TXN174312013F15	868799	TXN174312013FY7	891487
TXN174312013F16	872835	TXN174312013FY8	891483
TXN174312013F17	872848	TXN174312013FY9	891489
TXN174312013F27	884628	TXN174312013FYA	891484
TXN174312013F18	872849	TXN174312013FYB	891488

Reference Documents / Attachments:

Document:	Location #:
Qual Data	Please Contact your Local Intel Field Sales Representative

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
September 24, 2007	00	Originally Published PCN
October 15, 2007	01	Change to Qual Data Availability Date
October 31, 2007	02	Removed Incorrect Qualification Date verbiage and Added New End Cap and Packaging Box.

November 21, 2007	03	Added changes to PCB to improve ESD and EMI performance